



PRODUCT IDENTIFICATION

JRPI	1235	M	-	4R7	M
Type	Size	Material		Inductance	Tol.

FEATURES

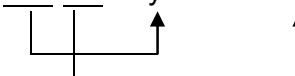
1. Carbonyl Powder.
2. Compact design.
3. High current , low DCR , high efficiency.
4. Very low acoustic noise and very low leakage flux noise.
5. High reliability.
6. 100% Lead(Pb)-Free and RoHS compliant.

Marking and Date code:

Marking ex:4.7(μH) → 4R7

Date code

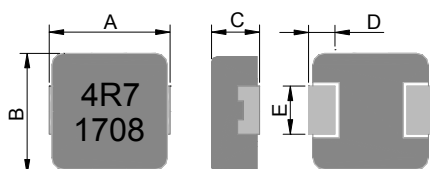
17 08 → year and weekly



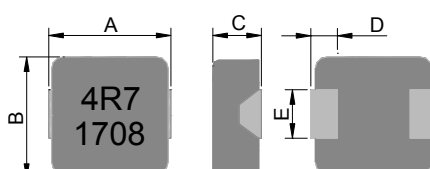
APPLICATIONS

Note PC power system , incl. IMVP-6 DC/DC converter .

DIMENSIONS (mm)



leadframe

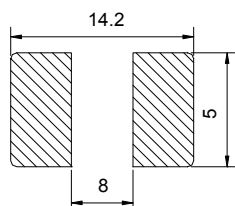


non-leadframe



印字:黑色4R7及D/C 1708 (17年,08週期)(依實際生產日期而定)

Recommend PC Board Pattern



Note:

1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.15mm and above.

Part No.	Size (mm)				
	A	B	C	D	E
JRPI 1235M	13.5 ± 0.5	12.5 ± 0.3	3.3 ± 0.2	2.3 ± 0.3	4.7 ± 0.3

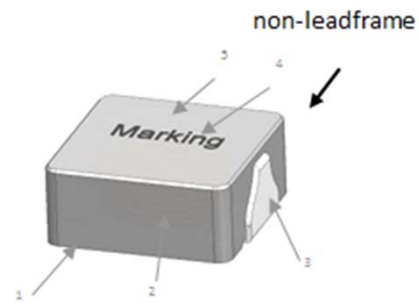
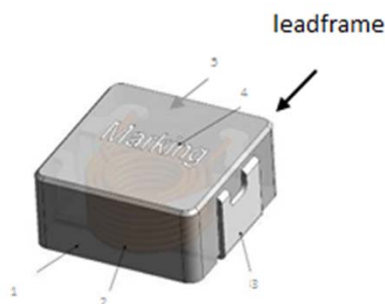
SERIES LIST

No.	Part No.	L	TOL.	RDC (mΩ)		Isat (A)	Irms (A)	Type
		(μH)	(%)	Typ.	Max.	Typ.	Typ.	
1	JRPI 1235M-R33M	0.33	±20	0.85	1.00	62.0	36.5	non-leadframe
2	JRPI 1235M-R36M	0.36	±20	0.87	1.10	60.0	36.0	non-leadframe
3	JRPI 1235M-R45M	0.45	±20	1.05	1.50	58.0	33.0	non-leadframe
4	JRPI 1235M-R47M	0.47	±20	1.20	1.80	55.0	32.0	non-leadframe
5	JRPI 1235M-R56M	0.56	±20	1.30	1.90	53.0	30.0	non-leadframe
6	JRPI 1235M-R60M	0.60	±20	1.50	2.20	51.0	29.0	non-leadframe
7	JRPI 1235M-R67M	0.67	±20	1.90	2.50	49.0	28.0	non-leadframe
8	JRPI 1235M-R68M	0.68	±20	1.90	2.50	49.0	28.0	non-leadframe
9	JRPI 1235M-R82M	0.82	±20	2.20	3.00	44.0	25.0	leadframe
10	JRPI 1235M-1R0M	1.00	±20	2.70	3.50	40.0	24.0	leadframe
11	JRPI 1235M-1R2M	1.20	±20	4.00	5.00	37.0	21.0	leadframe
12	JRPI 1235M-1R5M	1.50	±20	4.80	5.50	35.0	19.0	leadframe
13	JRPI 1235M-1R8M	1.80	±20	5.20	7.00	30.0	17.0	leadframe
14	JRPI 1235M-2R2M	2.20	±20	6.30	8.00	29.0	16.0	leadframe
15	JRPI 1235M-3R3M	3.30	±20	11.00	13.50	27.0	12.0	leadframe
16	JRPI 1235M-4R7M	4.70	±20	15.30	18.20	24.0	10.0	leadframe
17	JRPI 1235M-5R6M	5.60	±20	18.0	22.0	19.0	9.5	leadframe
18	JRPI 1235M-6R8M	6.80	±20	20.0	24.0	18.0	9.0	leadframe
19	JRPI 1235M-8R2M	8.20	±20	23.0	28.0	16.0	8.5	leadframe
20	JRPI 1235M-100M	10.0	±20	29.0	34.0	14.0	7.0	leadframe
21	JRPI 1235M-330M	33.0	±20	132.0	160.0	6.0	3.5	leadframe

Note:

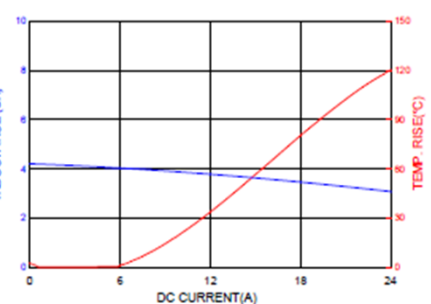
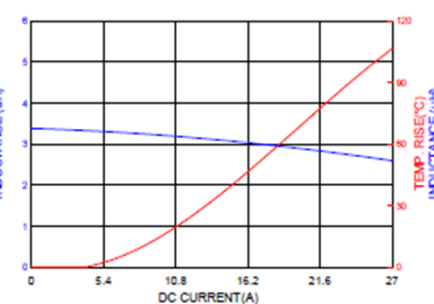
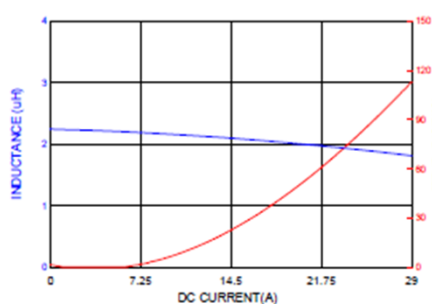
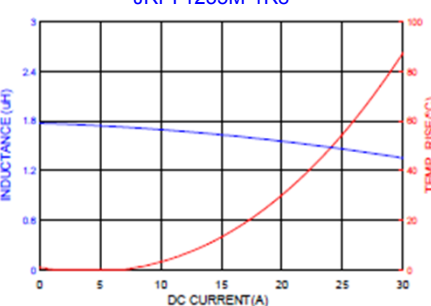
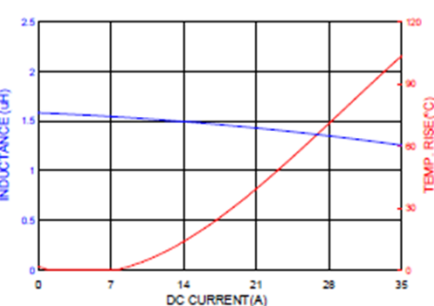
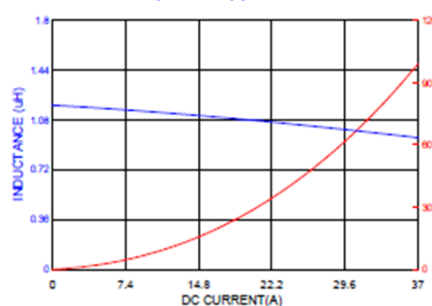
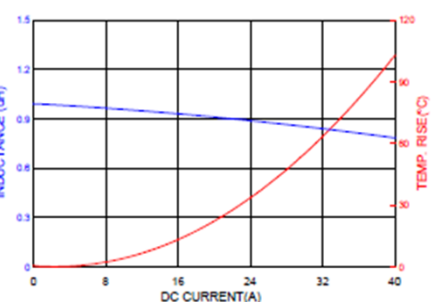
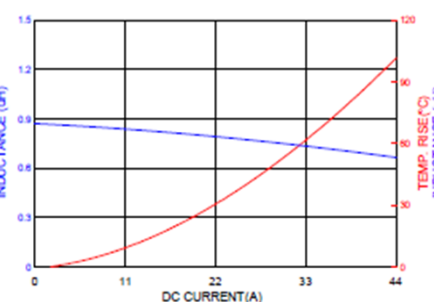
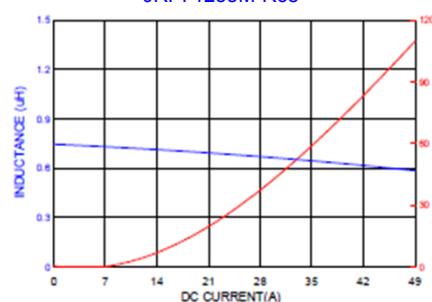
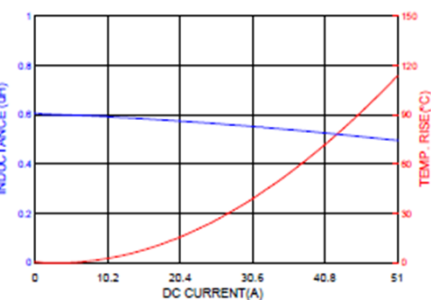
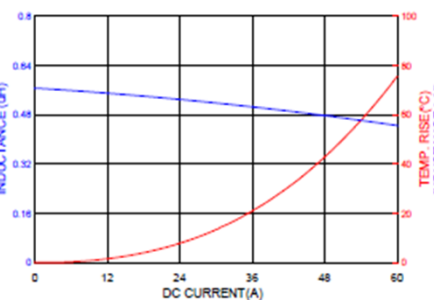
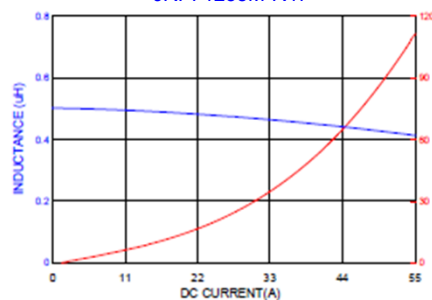
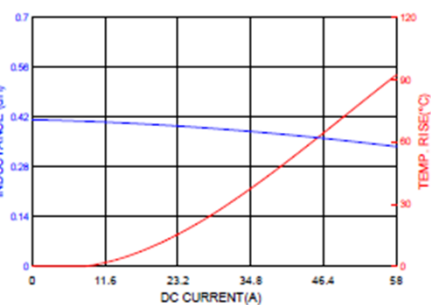
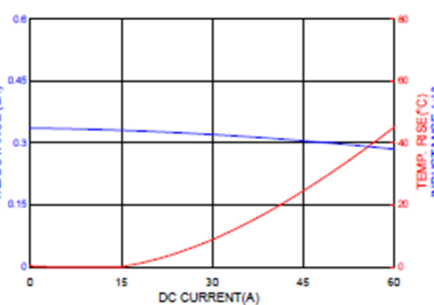
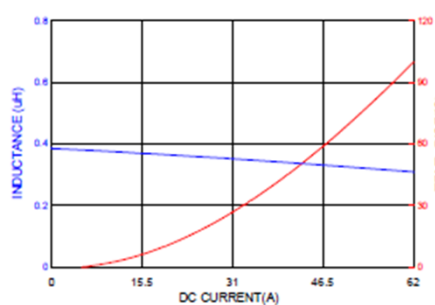
1. Test Frequency: 100KHz /1V
2. All test data referenced to 25°C ambient
3. Saturation Current (Isat) will cause L0 to drop approximately 30%
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.
Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
6. Special inquiries besides the above common used types can be met on your requirement.

Materials

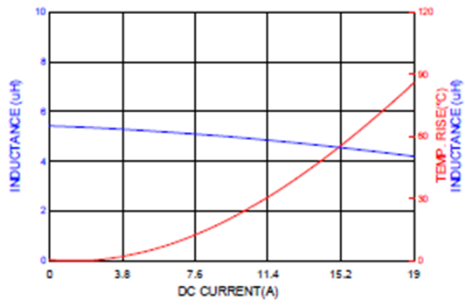


NO	Items	Materials
1	Core	Carbonyl Powder
2	Wire	Polyester Wire or equivalent
3	Clip	100% Pb free solder(Ni+Sn---Plating)
4	Ink	Halogen-free ketone
5	paint	Epoxy resin

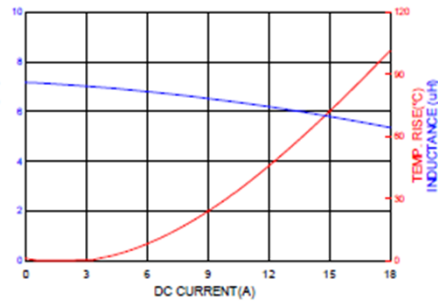
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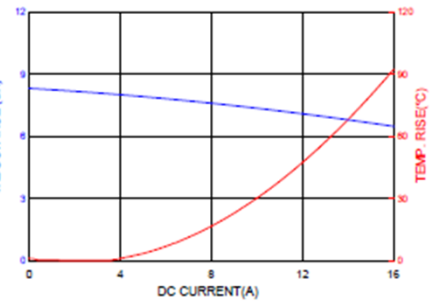
JRPI 1235M-5R6



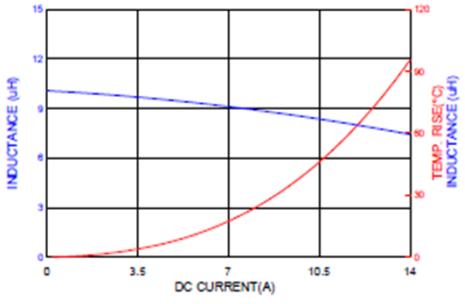
JRPI 1235M-6R8



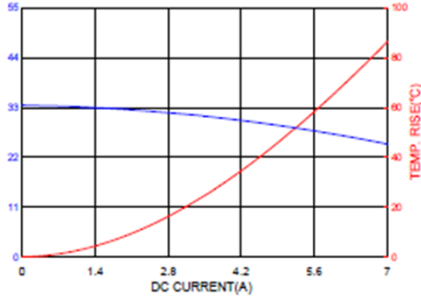
JRPI 1235M-8R2



JRPI 1235M-100

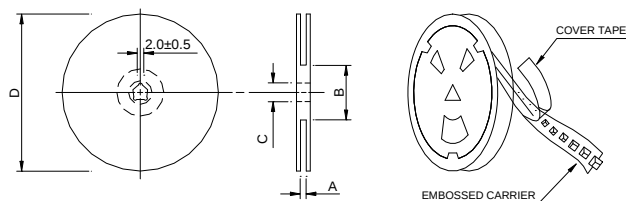


JRPI 1235M-330



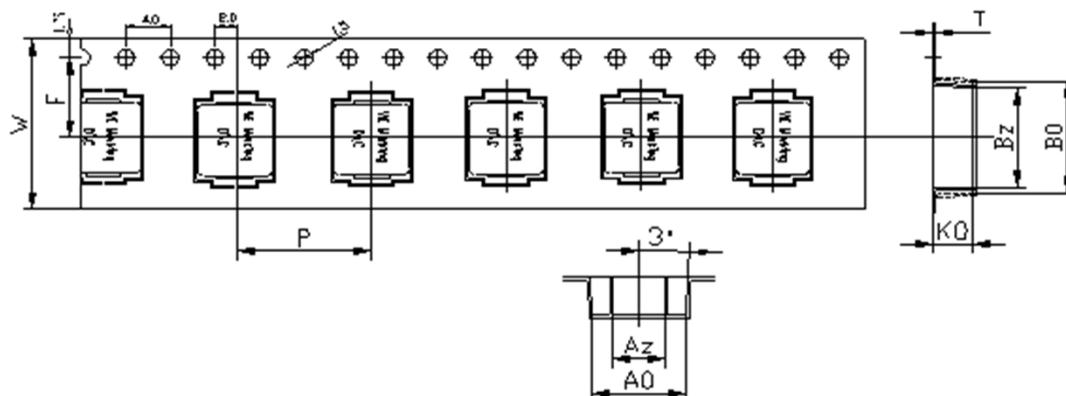
Packaging Information

• Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x24mm	24.4+2/-0	100±2	13+0.5/-0.2	330

• Tape Dimension

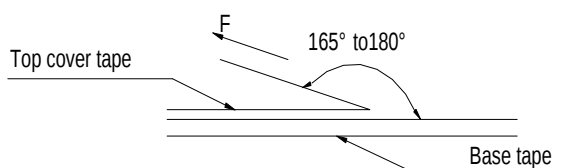


Ao(mm)	Az(mm)	Bo(mm)	Bz(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	t(mm)
12.9±0.1	7.0±0.1	14.1±0.1	13.0±0.1	4.0±0.1	16.0±0.1	24±0.3	11.5±0.1	0.35±0.05

• Packaging Quantity

Size	Reel	Inner box	Carton
JRPI 1235M	500	1000	4000

• Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions (referenced ANSI/EIA-481-C-2003 of 4.11 standard)

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

■ Application Notice

- Storage Conditions(component level)

To maintain the solderability of terminal electrodes:

1. Products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40°C and 60% RH.
3. Recommended products should be used within 12 months form the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

- Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.